

Production test Socket for NXP's FLIP CHIP SIP

Socket and Test your 14x10mm BGA device using extreme temperature socket

EAGAN, MN - December, 2016 - Ironwood Electronics recently introduced a new [Stamped spring pin socket](#) addressing high performance requirements for testing BGA208 - CBT-BGA-7041. The contactor is a [stamped spring pin](#) with 31 gram actuation force per ball and cycle life of 125,000 insertions. The self inductance of the contactor is 0.88 nH, insertion loss < 1 dB at 15.7 GHz and capacitance 0.097pF. The current capacity of each contactor is 4 amps at 40C temperature rise. Socket temperature range is -55°C to +180°C. Socket [features](#) a clamshell lid design for ease of chip replacement in production environment. It also has an integrated compression plate for vertical force without distorting device position. The specific configuration of the package to be tested in the CBT-BGA-7041 is a BGA, 14x10mm, 0.75mm pitch 16x13 array with 208 balls. The socket is mounted using supplied hardware on the target PCB with no soldering, and uses the smallest footprint in the industry. The smallest footprint allows inductors, resistors and decoupling capacitors to be placed very close to the device for impedance tuning. To use, place BGA device into the socket and close the lid by snapping to the latch. Vertical force is applied by turning the compression screw integrated into the socket lid. This socket can be used for quick device screening, device characterization at extreme temperatures as well as final production test.



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